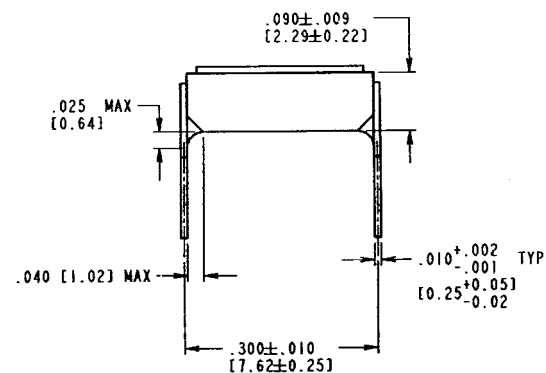
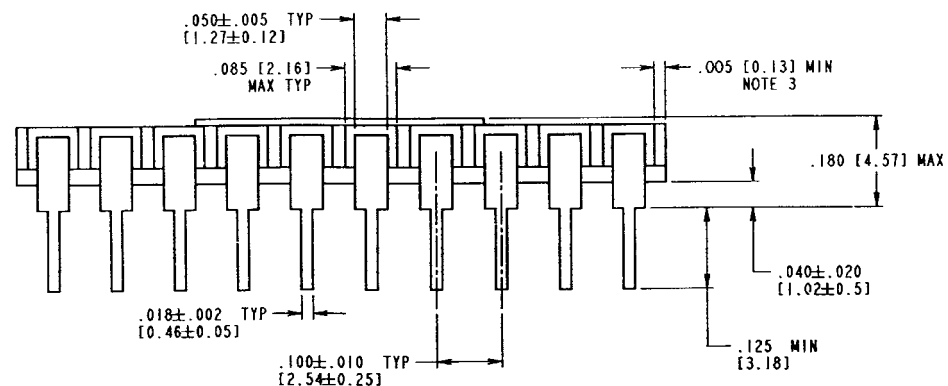
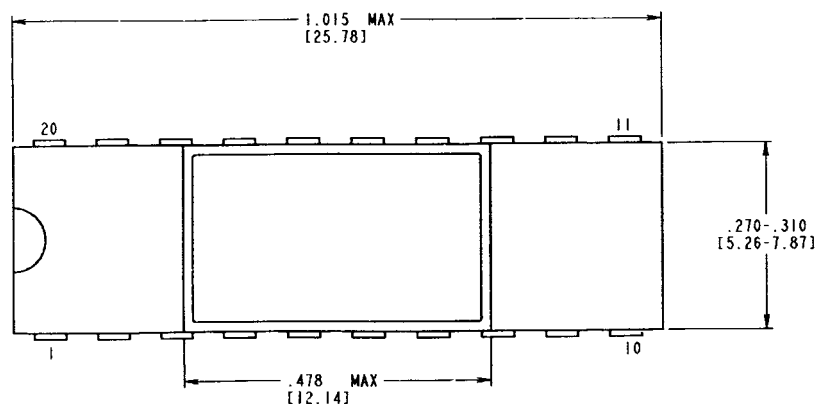




NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:

- 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
- 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.

2. LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.

3. DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.

4. REFERENCE JEDEC REGISTRATION MS-015, VARIATION AE, DATED 7/90.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW PER NEW STANDARD.	10259	02/16/94	DEG/TP
F	.085 MAX WAS .080 ± .008; .270-.310 WAS .290 ± .003.	10472	07/01/94	DEG/200

MIL/AERO
CONFIGURATION CONTROL

MIL-M-38510
CONFIGURATION CONTROL

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION	
DRN	Drayce Grady	02/16/94	2000 Semiconductor Drive, Santa Clara, CA 95052-8090	
DES. CH	<i>[Signature]</i>	7-794	DIP, SIDEBRAZED CERAMIC, 20 LEAD	
ENG. CH	<i>[Signature]</i>	7-794		
APPROVAL	<i>[Signature]</i>		SCALE	SIZE
		1 INCH (25.4)	N/A	C
			DO NOT SCALE DRAWING	
			DRAWING NUMBER	REV
			MKT-D20A	F
			SHEET 1 of 1	